# 2SC4626J

### Silicon NPN epitaxial planar type

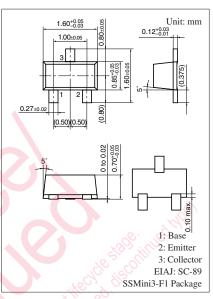
For high-frequency amplification

#### Features

- Optimum for RF amplification of FM/AM radios
- $\bullet$  High transition frequency  $f_{\rm T}$
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Symbol Rating	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	v
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V
Collector current	I <sub>C</sub>	30	mA
Collector power dissipation	P <sub>C</sub>	125	mW
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C



#### Marking Symbol: V

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 10 V, I_E = 0$			0.1	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}$	70		220	_
Transition frequency	f <sub>T</sub>	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$	150	250		MHz
Noise figure	NF	$V_{CB} = 10 \text{ V}, \text{ I}_{\text{E}} = -1 \text{ mA}, \text{ f} = 5 \text{ MHz}$		2.8	4.0	dB
Reverse transfer impedance	Z <sub>rb</sub>	$V_{CB} = 10 \text{ V}, \text{ I}_{\text{E}} = -1 \text{ mA}, \text{ f} = 2 \text{ MHz}$		22	50	Ω
Common-emitter reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		0.9	1.5	pF

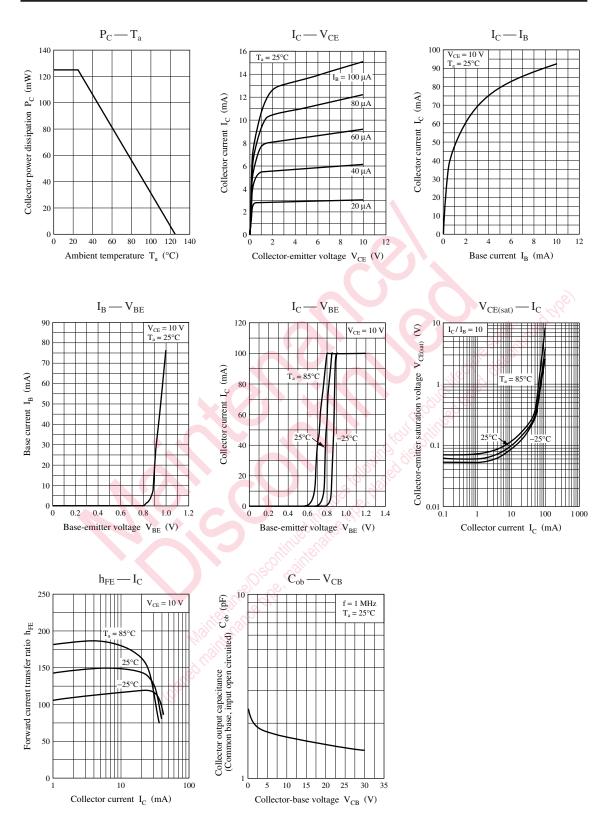
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2.	. *: Kank classification							
	_						Γ	

Rank	B	С	No-rank
$h_{\rm FE}$	70 to 140	110 to 220	70 to 220

Product of no-rank is not classified and have no indication for rank.

### Panasonic



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